KYOCERA KE-200DH

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

We have several grades of compounds w/good balance between cost and performance to meet wide requirements of customers.
Strong Points
Good Adhesion Strength even Under High Temperature Reflow Soldering Process.
Achieve Good Reflow Resistance (JEDEC Level 2) with Good Moldability.
JEDEC Level 1 in Case Smaller Package is possible.
Line Up for Several Lead Frame Types. (Cu,42Alloy,Pd/Au plated)
Application
SOP, Larger QFP, Smaller QFP, DIP, TO-PKG, DPAK, SOT

General Information		
Features	Good Adhesion Good Moldability	
Uses	Electrical/Electronic Applications	
Physical	**Nominal Value**	**Unit**
Specific Gravity	2.00	g/cm³
Spiral Flow	85.0	cm
Mechanical	**Nominal Value**	**Unit**
Flexural Modulus	18000	MPa
Flexural Strength	145	MPa
Thermal	**Nominal Value**	**Unit**
Glass Transition Temperature	130	°C
CLTE - Flow		
-- [1]	1.1E-5	cm/cm/°C
-- [2]	4.5E-5	cm/cm/°C
Uncured Properties	**Nominal Value**	**Unit**
Gel Time	0.38	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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WECHAT